

REMARKS

The issues outstanding in the Office Action mailed September 23, 2003, are the rejections under 35 U.S.C §§102 and 103. Reconsideration of these issues, in view of the following discussion is respectfully requested.

At the outset, it is submitted that there is clarification needed as to the first rejection in the Office Action that at pages 3-6.

First, at page 2, under "Disposition of Claims", it is indicated that claims 3 and 4 are withdrawn, and claim 1, 2 and 5-21 are rejected. However, at "page 2" of the Office Action (actually page 3 if the cover sheet is counted) it is indicated that claims "2,3 and 4" were withdrawn. Clarification of the status of claim 2 is therefore respectfully requested.

Second, the rejection under 35 U.S.C §102, set forth in page 3 of the Office Action, indicates only that claim 1 is rejected under 35 U.S.C §102. See item 3 on that page. However, the subsequent pages of the Office Action appear to apply the rejection to claims 2, 6, 7, 8, 14, 15, 16, 17, 18, 19, 20 and 21. Thus, clarification of the status of the claims mentioned at 3-6 of the Office Action, other than claim 1, is also respectfully requested.

With respect to the rejection of claim 1 under 35 U.S.C §102, it will be recalled Laing discloses a cooling device for a semiconductor apparatus comprising a chamber enclosing a non-metallic crystal forming material which can undergo a phase change at a temperature which corresponds to the desired operating temperature of the semiconductor component. More specifically, the semiconductor component that is in heat conductive communication is substantially thermally insulated (col. 2, lines 58-62). The operational nature of the Laing cooling device requires that there is a prerequisite temperature (optimum operating temperature of the semiconductor) which must be met before the crystal forming material will actually undergo the phase change and result in cooling (col. 2, lines 62-67). Moreover, the layers of the crystal forming material which are directly adjacent to the semiconductor will undergo a phase change and melt while those layers which are further removed from the semiconductor will remain substantially at room temperature (col. 2, line 67 - col.3, line 5).

Thus, in the Laing device, the electronic component is rapidly heated to the operating

temperature, since, before that temperature is reached, the phase change material (in intimate contact therewith) does not dissipate heat. The semiconductor component of the Laing device is in fact considered substantially thermally insulated (col.2, lines 60-61). As a result, the device of Laing is clearly of the conventional sort of heat sink design where the phase change material first has to heat before the heat can be dissipated via the cooling fins. There can be no loss of heat from the system until the semiconductor reaches the critical optimum temperature, as is desirable where fast heat up to operating temperature is needed.

However, at page 3, the Office Action argues that Laing *does* disclose a device "wherein the phase change material is arranged in such a way that the heat flows from the electrical or electronic component is [sic] preferentially to the heat conducting unit 1 (see FIG. 1) and a majority of heat flow to the phase change material from the electrical or electronic component occurs only when the temperature of the conducting unit 1 exceeds phase change temperature of the phase change material." However, this interpretation of FIG. 1 of the patent is impossible. In order for a majority of heat flow to the phase change material from the electronic component to occur *only* when the temperature of the conducting unit exceeds phase change temperature of the phase change material, there would have to be some means in the patent to prevent heat flow to the phase change unit unless the heat conducting unit, the fins in the patent, were at a temperature exceeding the phase change temperature of the phase change material. Since the path to the fins in the patent is *interrupted* by the phase change material, in order to insure that heat is not dissipated until the phase change temperature is reached, such interpretation of the drawing as in the Office Action is simply not possible. The patent drawing clearly shows that no heat flow can reach the fins until heat is dissipated by the phase change material, which dissipation does not occur until the phase change material reaches phase change temperature. Clearly, this drawing can neither anticipate nor suggest heat flow to the fins from the electrical or electronic component *only* when the temperature of the fins exceeds the phase change temperature. Instead, heat flow in the referenced figure goes to the heat conducting unit (the fins) only *after* the temperature of the phase change material is exceeded. Thus, heat flow to the phase change material in the reference occurs *long before* the temperature of the heat conducting unit exceeds the phase change temperature of the phase change material. There simply cannot be an

anticipation by the reference.

With respect to claims 2, 6 and 7, mentioned at page 4 of the Office Action, these claims are dependent upon claim 1, and thus also cannot be anticipated by the reference.

With respect to claim 14, also mentioned at page 4 of the Office Action, as discussed above, the reference in no way discloses a device wherein heat flows from the heat source to the heat sink, and flows from the heat sink to the heat absorbing component when the heat sink temperature exceeds the phase change temperature of the phase change material. Instead, in the reference, heat flows from the phase change material to the heat sink, and only when the temperature of the phase change material is exceeded. Heat flow is not *from* the heat sink to the phase change material, as in claim 14, but quite the opposite. Thus, this claim also cannot be anticipated by the reference. Similar issues apply to claim 15. While it is noted that, at page 4, the Office Action argues that "intended use" statements in the claims are not given any weight, the above noted language is not intended use but defines orientation of the components of the device claimed. Thus, the orientation of the components, which directs heat flow in a way which is neither disclosed or suggested in the reference, must be given weight. In short, mapping of the heat flow path is a apparatus limitation.

With respect to claim 16, similar issues apply. The prior art neither discloses nor suggests the *apparatus configuration* in which heat flows from the heat generating electric or electronic component to the heat sink, and from the heat sink to the heat absorbing component when the heat sink temperature exceeds the phase change temperature of the phase change material. The configuration disclosed in the reference is quite the opposite, as discussed above.

With respect method claims 17-19, similar issues apply, inasmuch as the reference cannot disclose a method for absorbing heat in which heat flows from a heat sink to a heat absorbing component when the heat sink temperature exceeds the phase change temperature of the phase change material, inasmuch as the flow in the reference is the opposite; heat flows from the phase change material to the heat sink only when the phase change temperature is exceeded. Similar issues apply to claims 18 and 19, which are dependent upon claim 17.

With respect to claims 20 and 21, these claims are dependent upon claims 1 and 14, respectively, and also are not anticipated as discussed above.

In conclusion, withdrawal of all of the rejections under 35 U.S.C §102 over Laing is respectfully requested.

Claims 9, 10, 11 and 12 have been rejected under 35 U.S.C §102(b) or, in the alternative 103 over Maruyama, et al. '242. Reconsideration of this rejection is respectfully requested. It is assumed, in fact, that this rejection is intended to be one over Laing *taken with* Maruyama, inasmuch as both references are discussed at page 6 of the Office Action. The deficiencies of Laing are discussed above and Maruyama does nothing to remedy the lack of a disclosure of an apparatus or method in which the components are structured so that heat flows as prescribed. Thus, this rejection should also be withdrawn.

Claim 5 has been rejected under 35 U.S.C §103 over Laing taken with Fitch, et al., '321. Reconsideration of this rejection is also respectfully requested. The deficiencies of Laing are discussed at length above. Fitch, cited solely for the use of a particular phase change material, does nothing to remedy these deficiencies, and withdrawal this rejection is therefore also respectfully requested.

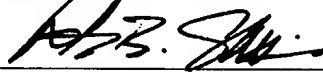
Finally, claim 13 has been rejected under 35 U.S.C §103 over Laing taken with Bunyan, et al. '198. As noted above, Bunyan is cited for a particular feature of a dependent claim, and does nothing to remedy the deficiencies of the primary reference. Thus, withdrawal of this rejection is also respectfully requested.

In conclusion, the claims of the application are submitted to be in condition for allowance, inasmuch as Laing discloses an apparatus in which the components are configured in an opposite manner to that presently claimed. Thus, the reference cannot and does not anticipate, much less suggest, the present claims. Withdrawal of all the rejections is respectfully requested.

Should the Examiner have any questions or comments, he or she is cordially invited to telephone the undersigned at the number below.

The Commissioner is hereby authorized to charge any fees associated with this response or credit any overpayment to Deposit Account No. 13-3402.

Respectfully submitted,



Harry B. Shubin, Reg. No. 32,004
Attorney/Agent for Applicant(s)

MILLEN, WHITE, ZELANO
& BRANIGAN, P.C.
Arlington Courthouse Plaza 1, Suite 1400
2200 Clarendon Boulevard
Arlington, Virginia 22201
Telephone: (703) 243-6333
Facsimile: (703) 243-6410

Attorney Docket No.: MERCK 2276

Date: December 22, 2003

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